

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 11-190787

(43)Date of publication of application : 13.07.1999

(51)Int.Cl.

G21B 1/00
B23K 20/00
B23K 20/00
// B23K103:18

(21)Application number : 09-360223

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(22)Date of filing : 26.12.1997

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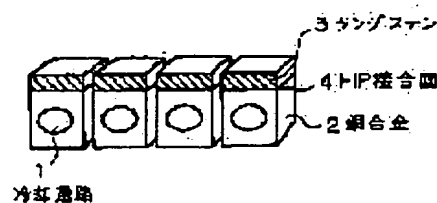
FUKAYA KIYOSHI

(54) HEAT RESISTANT DIRECT JOINT STRUCTURE OF HIGH MELTING POINT MATERIAL AND HIGH THERMAL CONDUCTIVITY MATERIAL OR JOINTING METHOD THEREFOR

(57)Abstract:

PROBLEM TO BE SOLVED: To enhance uniformity at joint and joint efficiency by composing the cooling passage of a fusion reactor of a copper alloy having high thermal conductivity and composing a cooling plate of tungsten.

SOLUTION: A fusion reactor comprises a vacuum vessel, a coil generating a field for confining a hydrogen isotope plasma and a cooling passage 1 for passing coolant arranged in the vacuum vessel, and a cooling plate having a material facing plasma. A member having the cooling passage 1 is composed of a copper alloy 2 having high thermal conductivity and the cooling plate is composed of tungsten 3 having high melting point. The copper alloy 2 and tungsten 3 are jointed directly through an HIP(high pressure isotropic pressure) joint face 4 without using any brazing material. Direct jointing is performed under temperature of 900-1,100°C by applying a high pressure of 50-200 MP isotropically for 0.15-4 hours.



LEGAL STATUS

[Date of request for examination] 05.07.2000

[Date of sending the examiner's decision of rejection] 02.10.2001

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection] 2001-19359

[Date of requesting appeal against examiner's decision of rejection] 30.10.2001

[Date of extinction of right]

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